18-60Vdc Input; 8Vdc, 4.2A, 34W Output



Applications

- Wireless Networks
- Hybrid power architectures
- **Optical and Access Network Equipment**
- Enterprise Networks including Power over Ethernet (PoE)
- Industrial markets

Options

- Negative Remote On/Off logic (preferred)
- Auto-restart Over current/Over voltage protections (preferred)
- Shorter through hole pin trim

Features

- Compliant to RoHS EU Directive 2002/95/EC (-Z versions)
- Input Voltage Range, 18Vdc to 60Vdc
- No minimum load
- High efficiency 90% at full load (V_{IN}=48V_{dc})
- Constant switching frequency
- Low output ripple and noise
- Small Size and low profile, follows DOSA standard 1/16th footprint 33.0 mm x 22.9 mm x 9.3mm (1.30 in x 0.9 in x 0.37in)
- Reflow process compliant
- Positive Remote On/Off logic
- Output overcurrent/voltage protection (hiccup)
- Over-temperature protection
- Output Voltage adjust: 80% to 110% of Vo,nom
- Wide operating temperature range (-40°C to 80°C)
- UL*Recognized to UL60950-1, CAN/CSA⁺ C22.2 No.60950-1. and EN60950-1(VDE [‡] 0805-1) Licensed
- CE mark meets 2006/95/EC directive§
- Meets the voltage and current requirements for ETSI 300-132-2 and complies with and licensed for Basic insulation rating per EN60950-1
- 2250 Vdc Isolation tested in compliance with IEEE 802.3[¤] PoE standards
- ISO** 9001 and ISO 14001 certified manufacturing facilities

Description

The KHHD004A2S8R0 series of Power Input Modules are identical in form, fit and function to the parent KHHD004A2B Hammerhead™ Series; DC-DC Converter Power Modules with the noted exceptions.

UL is a registered trademark of Underwriters Laboratories. Inc.

- CSA is a registered trademark of Canadian Standards Association. VDE is a trademark of Verband Deutscher Elektrotechniker e.V.
- This product is intended for integration into end-user equipment. All of the required procedures of end-use equipment should be followed.

= IEEE and 802 are registered trademarks of the Institute of Electrical and Electronics Engineers, Incorporated ** ISO is a registered trademark of the International Organization of Standards.

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Absolute Maximum Ratings

Stresses in excess of the absolute maximum ratings can cause permanent damage to the device. These are absolute stress ratings only, functional operation of the device is not implied at these or any other conditions in excess of those given in the operations sections of the data sheet. Exposure to absolute maximum ratings for extended periods can adversely affect the device reliability.

Parameter		Symbol	Min	Max	Unit
Input Voltage (Continuous)		V _{IN}	-0.3	60	Vdc
Transient (100ms)		V _{IN, trans}	-0.3	80	Vdc
Operating Ambient Temperature		TA	-40	80	°C
(see Thermal Considerations section)					
Storage Temperature		T _{stg}	-55	125	°C
Altitude*	All			4000	m
I/O Isolation Voltage (100% factory Hi-Pot tested)		_	_	2250	Vdc

* For higher altitude applications, contact your GE Sales Representative for alternative conditions of use.

Electrical Specifications

Unless otherwise indicated, specifications apply at $V_{IN} = 48V_{dc}$, resistive load, and $T_A = 25^{\circ}C$ conditions.

Parameter		Symbol	Min	Тур	Max	Unit
Operating Input Voltage	All	V _{IN}	18	24/48	60	V _{dc}
Input No Load Current	All	I _{IN.No load}		40	50	mA
$(I_{0} = 0A, module enabled)$		IN,NO IODD		40	50	ША
Input Stand-by Current	All	las en es		8		mA
$(V_{IN} = 24 \text{ to } 48V_{dc}, \text{ module disabled})$		I _{IN,stand-by}		0		ША
Maximum Input Current (V_IN=18V_{dc}, I_O=I_{O,MAX})	All	I _{IN, MAX}			2.2	A _{dc}
Inrush Transient	All	l²t			0.05	A ² s
Input Reflected Ripple Current, peak-to-peak (5Hz to 20MHz, 12µH source impedance; V _{IN} =0V to 75V _{dc} , I ₀ = I _{Omax} ; see Test configuration section)	All			30		mA _{p-p}
Input Ripple Rejection (120Hz)	All			60		dB
EMC, EN55022		See EMC Considerations section				

CAUTION: This power module is not internally fused. An input line fuse must always be used.

This power module can be used in a wide variety of applications, ranging from simple standalone operation to being part of complex power architecture. To preserve maximum flexibility, internal fusing is not included; however, to achieve maximum safety and system protection, always use an input line fuse. The safety agencies require a fast-acting fuse with a maximum rating of 6A (see Safety Considerations section). Based on the information provided in this data sheet on inrush energy and maximum dc input current, the same type of fuse with a lower rating can be used. Refer to the fuse manufacturer's data sheet for further information.

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Electrical Specifications (continued)

Unless otherwise indicated	specifications apply at at $V_{IN} = 48V_{dc7}$ resistive load, and $T_A = 25$	°C conditions
offices otherwise indicated	specifications apply at at VIN TOVUC, resistive load, and IA Es	o contantionio.

Parameter		Symbol	Min	Тур	Max	Unit
Output Voltage Set-point (V _{IN} =24 to 48V _{dc} , I _O =I _{O, max} ,)	All	V _{O, set}	7.88	8.00	8.12	V _{dc}
Output Voltage (Over all operating input voltage, resistive load, and temperature conditions until end of life)		Vo	-3.0 (7.76)	_	+3.0 (8.24)	% V _{O, set}
Adjustment Range Selected by external resistor	All	V _{O, adj}	-20		+10	% V _{O, set}
Remote Sense Range	All				+10	% V _{O, set}
Output Regulation Line (V _{IN} =V _{IN, min} to V _{IN, max}) Load (I _o =I _{o, min} to I _{o, max}) Temperature (T _{ref} =T _{A, min} to T _{A, max}) Output Ripple and Noise on nominal output				0.05 0.05 —	0.2 0.2 1.0	% V _{O, set} % V _{O, set} % V _{O, set}
Measured with 10uF Tantalum 1uF ceramic (V _{IN} =24 to 48V _{dc} , I ₀ =80%I _{0, max}) RMS (5Hz to 20MHz bandwidth) Peak-to-Peak (5Hz to 20MHz bandwidth)				25 100	40 150	mV _{rms} mV _{pk-pk}
External Capacitance (see Note 1 in Feature Specifications)	All	C _{O, max}	0		2200	μF
Output Current (over temperature range) Output Current Limit Inception (Hiccup Mode)		l _o I _{O, lim}	0 4.62	_	4.2 5.88	A _{dc}
Output Short-Circuit Current ($V_0 \le 250 \text{ mV}$)	All	I _{O, s/c}		2.5	_	A _{rms}
Efficiency (V _{IN} =24V _{dc} , I _O =I _{O, max})	All	η	89.0	90.0	_	%
Efficiency (V _{IN} =48V _{dc} , I _O =I _{O, max})	All	η	89.0	90.0		%
Switching Frequency (Fixed) VIN=24 to 48Vdc, Io= Io, max		f _{sw}		300		kHz
Dynamic Load Response (Δ lo/ Δ t=0.1A/µs, V _{IN} =24 to 48Vdc) Load Change from Io= 50% to 75% or 25% to 50% of I _{o,max} :						
Peak Deviation Settling Time (Vo<10% peak deviation)		V _{pk} t _s	_	3.0 400		% V _{O, set} μS

Isolation Specifications

Parameter	Symbol	Min	Тур	Max	Unit
Isolation Capacitance	C _{iso}	_	1000	_	pF
Isolation Resistance	R _{iso}	10	_	_	MΩ
I/O Isolation Voltage	All		_	2250	Vdc

General Specifications

Parameter		Min	Тур	Max	Unit
Calculated Reliability based upon Telcordia SR-332 Issue 2: Method I Case 3 (Io=80%Io, max, TA=40°C, airflow = 200 lfm, 90% confidence)		261.1		10 ⁹ /Hours	
			3,829,239		Hours
Weight		—	13 (0.46)	_	g (oz.)

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Feature Specifications

Unless otherwise indicated, specifications apply at $V_{IN} = 48V_{dc}$, resistive load, and $T_A = 25$ °C conditions. See Feature Descriptions for additional information.

Parameter	Device	Symbol	Min	Тур	Max	Unit
Remote On/Off Signal Interface						
$(V_{\text{IN}}{=}V_{\text{IN, min}} \text{ to } V_{\text{IN, max}}\text{; open collector or equivalent,}$						
Signal referenced to $V_{\text{IN-}}$ terminal)						
Negative Logic: device code suffix "1"						
Logic Low = module On, Logic High = module Off						
Positive Logic: No device code suffix required						
Logic Low = module Off, Logic High = module On						
Logic Low - Remote On/Off Current ($V_{on/off} = -0.7V_{dc}$)	All	I _{on/off}	_	_	0.15	mA
Logic Low - On/Off Voltage (Module On)	All	V _{on/off}	-0.7	_	0.8	V _{dc}
Logic High Voltage ($I_{on/off} = OA_{dc}$) (Module Off)	All	V _{on/off}	2.4	_	7	V _{dc}
Logic High maximum allowable leakage current		I _{on/off}	_	_	25	μA
Turn-On Delay and Rise Times						
(I ₀ =80% of I _{0, max})						
Case 1: Input power is applied for at least 1second, and then the On/Off input is set from OFF to ON ($T_{delay} = on/off$ pin transition until $V_0 = 10\%$ of $V_{0, set}$)	All	T _{delay} Case1	_	30	50	ms
Case 2: On/Off input is set to Module ON, and then input power is applied $(T_{delay} = V_{IN} \text{ reaches } V_{IN, min} \text{ until } V_0 = 10\% \text{ of } V_{O,set})$	All	T _{delay} _{Case2}	_	20	50	ms
Output voltage Rise time (time for V_{o} to rise from 10% of $V_{o,set}$ to 90% of $V_{o,set})$	All	T _{rise}	_	5	10	ms
Output Voltage Overshoot					3	% V _{O, set}
(I_0=80% of I_0, _max, V_1N= 24 to $48V_{dc}$)					5	70 VO, set
Output Overvoltage Protection ¹		V _{O, limit}	9.6	—	12.0	V _{dc}
Input Undervoltage Lockout						
Turn-on Threshold	All	V _{uv/on}	16	17	18	V _{dc}
Turn-off Threshold	All	V _{uv/off}	15	16	17	V _{dc}
Hysterisis	All	V _{hyst}	—	1.0	—	V _{dc}

Note: 1.The module requires a minimum of 220 µF external output capacitor to avoid exceeding the OVP maximum limits during startup into open loop fault conditions.

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Characteristic Curves

The following figures provide typical characteristics at 25°C. The figures are identical for either positive or negative remote On/Off logic.





Figure 1. Converter Efficiency versus Output Current.



TIME, t (2µs/div)





Figure 5.Typical Start-up Using Remote On/Off, negative logic version shown ($V_{IN} = 48V$, Io = $I_{o,max}$).

Figure 2. Converter Input Current versus Input Voltage.



TIME, t (200µs/div)





TIME, t (10ms/div)



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Test Configurations



NOTE: Measure input reflected ripple current with a simulated source inductance (L_{TEST}) of 12µH. Capacitor C_S offsets possible battery impedance. Measure current as shown above.

Figure 7. Input Reflected Ripple Current Test Setup.



NOTE: All voltage measurements to be taken at the module terminals, as shown above. If sockets are used then Kelvin connections are required at the module terminals to avoid measurement errors due to socket contact resistance.

Figure 8. Output Ripple and Noise Test Setup.



NOTE: All voltage measurements to be taken at the module terminals, as shown above. If sockets are used then Kelvin connections are required at the module terminals to avoid measurement errors due to socket contact resistance

Figure 9. Output Voltage and Efficiency Test Setup.

Efficiency
$$\eta = \frac{V_0. I_0}{V_{IN} I_{IN}} \times 100 \%$$

Design Considerations

Input Source Impedance

The power module should be connected to a low ac-impedance source. Highly inductive source impedance can affect the stability of the power module. For the test configuration in Figure 7, a 33 μ F electrolytic capacitor (ESR<0.7 Ω at 100kHz), mounted close to the power module helps ensure the stability of the unit. Consult the factory for further application guidelines.

Safety Considerations

For safety-agency approval of the system in which the power module is used, the power module must be installed in compliance with the spacing and separation requirements of the end-use safety agency standard, i.e., UL 60950-1-3, CSA C22.2 No. 60950-00, and VDE 0805 (IEC60950, 3rd Edition).

If the input source is non-SELV (ELV or a hazardous voltage greater than 60 Vdc and less than or equal to 75Vdc), for the module's output to be considered as meeting the requirements for safety extra-low voltage (SELV), all of the following must be true:

- The input source is to be provided with reinforced insulation from any other hazardous voltages, including the ac mains.
- One V_{IN} pin and one V_{OUT} pin are to be grounded, or both the input and output pins are to be kept floating.
- The input pins of the module are not operator accessible.
- Another SELV reliability test is conducted on the whole system (combination of supply source and subject module), as required by the safety agencies, to verify that under a single fault, hazardous voltages do not appear at the module's output.
- **Note:** Do not ground either of the input pins of the module without grounding one of the output pins. This may allow a non-SELV voltage to appear between the output pins and ground.

The power module has extra-low voltage (ELV) outputs when all inputs are ELV.

For input voltages exceeding -60 Vdc but less than or equal to -75 Vdc, these converters have been evaluated to the applicable requirements of BASIC INSULATION between secondary DC MAINS DISTRIBUTION input (classified as TNV-2 in Europe) and unearthed SELV outputs.

The input to these units is to be provided with a maximum 6A fast acting fuse in the ungrounded lead.

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Feature Description

Remote On/Off

Two remote on/off options are available. Positive logic turns the module on during a logic high voltage on the on/off pin, and off during a logic low. Negative logic remote on/off, device code suffix "1", turns the module off during a logic high and on during a logic low.



Figure 10. Circuit configuration for using Remote On/Off Implementation.

To turn the power module on and off, the user must supply a switch (open collector or equivalent) to control the voltage ($V_{on/off}$) between the ON/OFF terminal and the $V_{IN}(-)$ terminal. Logic low is $0V \le V_{on/off} \le 0.8V$. The maximum $I_{on/off}$ during a logic low is 0.15mA, the switch should be maintain a logic low level whilst sinking this current.

During a logic high, the typical V_{on/off} generated by the module is 4.0V, and the maximum allowable leakage current at V_{on/off} = 4.0V is 25μ A.

If not using the remote on/off feature:

For positive logic, leave the ON/OFF pin open.

For negative logic, short the ON/OFF pin to $V_{IN}(-)$.

Overcurrent Protection

To provide protection in a fault (output overload) condition, the unit is equipped with internal current-limiting circuitry and can endure current limiting continuously. At the point of current-limit inception, the unit enters hiccup mode. If the unit is not configured with auto-restart, then it will latch off following the over current condition. The module can be restarted by cycling the dc input power or by toggling the remote on/off signal. If the unit is configured with the autorestart option (4), it will remain in the hiccup mode as long as the overcurrent condition exists; it operates normally, once the output current is brought back into its specified range.

Overtemperature Protection

To provide protection under certain fault conditions, the unit is equipped with a thermal shutdown circuit. The unit will shut down if the thermal reference point Tref (Figure 16), exceeds 135°C (typical), but the thermal shutdown is not intended as a guarantee that the unit will survive temperatures beyond its rating. The module will automatically restart upon cool-down to a safe temperature.

Input Undervoltage Lockout

At input voltages below the input undervoltage lockout limit, the module operation is disabled. The module will only begin to operate once the input voltage is raised above the undervoltage lockout turn-on threshold, $V_{UV/ON}$.

Once operating, the module will continue to operate until the input voltage is taken below the undervoltage turn-off threshold, $V_{\text{UV/OFF}}.$

Over Voltage Protection

The output overvoltage protection shall consist of circuitry that independently monitors the output voltage, and shuts the module down if the output voltage exceeds specified limits. This protection feature latches in the event of over voltage across the output. Cycling the on/off pin or input voltage resets the latching protection feature. If the auto-restart option (4) is ordered, the module will automatically restart upon an internally programmed time elapsing.

Output Voltage Programming

Trimming allows the user to increase or decrease the output voltage set point of the module. This is accomplished by connecting an external resistor between the TRIM pin and either the Vout+ pin or the Vout- pin.

Trim Down – Decrease Output Voltage

By connecting an external resistor between the TRIM pin and Vout(-) pin ($R_{adj-down}$), the output voltage set point decreases (see figure 11). The following equation determines the external resistor value to obtain an output voltage change from $V_{o,set}$ to the desired $V_{o,desired}$:

$$R_{adj-down} = \left[\frac{511}{\Delta\%} - 10.22\right] k\Omega$$

Where $\Delta\% = \left(\frac{V_{o,set} - V_{o,desired}}{V_{o,set}}\right) \times 100$

Figure 11. Circuit Configuration to Decrease Output Voltage. Trim Up – Increase Output Voltage

By connecting an external resistor between the TRIM pin and Vout(+) pin (R_{adj-up}), the output voltage set point increases (see figure 12). The following equation determines the external resistor value to obtain an output voltage change from $V_{o,set}$ to the desired $V_{o,desired}$:

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Feature Descriptions (continued)





Figure 12. Circuit Configuration to Increase Output Voltage.

The combination of the output voltage adjustment and the output voltage initial tolerance must not exceed the allowable trim range of 80% to 110% of the nominal output voltage as measured between the Vout+ and Vout- pins.

The power modules have a fixed current-limit set point. Therefore, as the output voltage is adjusted down, the available output power is reduced.

Pre-bias Vin Under Voltage Test

The module shall recover from UVLO [Under Voltage Lock Out] without protective shutdown from OCP or OVP or hard failure, when subjected to Vin Under Voltage transients with the following conditions:

Vin(V)	Tdip (ms)	Co (uF)	Load (A)
48	5	0	0
48	5	2200	0
48	10	0	0
48	10	2200	0
48	5	0	4.2
48	5	2200	4.2
48	10	0	4.2
48	10	2200	4.2
60	5	0	0
60	5	2200	0
60	10	0	0
60	10	2200	0
60	5	0	4.2
60	5	2200	4.2
60	10	0	4.2
60	10	2200	4.2
	= 10us	Tdip -	ise = 5us
	5V — –		30 - 503

Thermal Considerations

The power modules operate in a variety of thermal environments; however, sufficient cooling should be provided to help ensure reliable operation.

Considerations include ambient temperature, airflow, module power dissipation, and the need for increased reliability. A reduction in the operating temperature of the module will result in an increase in reliability.

The thermal data presented here is based on physical measurements taken in a wind tunnel, using automated thermo-couple instrumentation to monitor key component temperatures: FETs, diodes, control ICs, magnetic cores, ceramic capacitors, opto-isolators, and module pwb conductors, while controlling the ambient airflow rate and temperature. For a given airflow and ambient temperature, the module output power is increased, until one (or more) of the components reaches its maximum derated operating temperature, as defined in IPC-9592A. This procedure is then repeated for a different airflow or ambient temperature until a family of module output derating curves is obtained.



Figure 13. Thermal Test Setup.

Heat Transfer via Convection

Increased airflow over the module enhances the heat transfer via convection. Derating figures showing the maximum output current that can be delivered by each module versus local ambient temperature (T_A) for natural convection.

Please refer to the Application Note "Thermal Characterization Process For Open-Frame Board-Mounted Power Modules" for a detailed discussion of thermal aspects including maximum device temperatures.

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Figure 14. Output Current Derating in the Transverse Orientation; Airflow Direction from Vin(-) to Vin(+); Vin = 24V.



Figure 15. Output Current Derating in the Transverse Orientation; Airflow Direction from Vin(-) to Vin(+); Vin = 48V.

The thermal reference point, T_{ref} , used in the specifications is shown in Figure 16. For reliable operation this temperature should not exceed 119°C.



Figure 16. T_{ref} Temperature Measurement Location.

EMC Requirements

Figure 17 shows a maximum filter configuration to meet the conducted emission limits of EN55022 Class B.

Notes: C1 and C4 are low impedance SMT ceramics.





Figure 18. Vin+ Line EMC signature using above filter, Vin=48V, Blue=Quasi Peak, Red=Average.

For further information on designing for EMC compliance, please refer to the FLTR100V10 data sheet (FDS01-043EPS).

Layout Considerations

The power module are low profile in order to be used in fine pitch system card architectures. As such, component clearance between the bottom of the power module and the mounting board is limited. Avoid placing copper areas on the outer layer directly underneath the power module. Also avoid placing via interconnects underneath the power module.

For additional layout guide-lines, refer to the FLTR100V10 data sheet.

Soldering Information

The RoHS-compliant (Z codes) through-hole products use the SAC (Sn/Ag/Cu) Pb-free solder and RoHS-compliant components. They are designed to be processed through single or dual wave soldering machines. The pins have an RoHS-compliant finish that is compatible with both Pb and Pb-free wave soldering processes. A maximum preheat rate of 3°C/s is suggested. The wave preheat process should be such that the temperature of the power module board is kept below

210°C. For Pb solder, the recommended pot temperature is

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Layout Considerations (continued)

260°C, while the Pb-free solder pot is 270°C max. Not all RoHScompliant through-hole products can be processed with pastethrough-hole Pb or Pb-free reflow process. If additional information is needed, please consult with your GE representative for more details.

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Mechanical Outline



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Recommended Pad Layout

Dimensions are in millimeters and [inches].

Tolerances: x.x mm \pm 0.5 mm [x.xx in. \pm 0.02 in.] (Unless otherwise indicated) x.xx mm \pm 0.25 mm [x.xxx in \pm 0.010 in.]



Pad Layout

For .025 x .030 rectangular pin, use a .050 diameter plated through hole For .062 diameter pin, use a .076 diameter plated through hole.

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Packaging Details

Tray Dimensions

The modules are supplied in trays as standard. Details of tray dimensions are shown below. Modules are shipped in quantities of 75 modules per box.

Dimensions are in millimeters.

Tolerances: x.x mm \pm 0.5 mm (unless otherwise indicated)



$\overline{}$
15.54±0.5

Material	
Max surface resistivity	
Color	
Capacity	
Min order quantity	

PET (1mm)

 $10^9\,\text{--}10^{11}\Omega/\text{PET}$

Clear 25power modules 75pcs (1 box of 3 full trays + 1 empty top tray)

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Ordering Information

Please contact your GE Sales Representative for pricing, availability and optional features.

Table 1. Device Codes

Product codes	Input Voltage	Output Current	Output Voltage	Remote On/Off Logic	Connector Type	Comcodes
KHHD004A2S8R0841Z	24V/48V (18-60Vdc)	4.2A	8.0V	Negative	Through hole	150036224

Table 2. Device Options

	Characteristic	Character and Position	Definition
	Form Factor	К	K = Sixteenth Brick
gs	Family Designator	HH	HH = Hammerhead Series
tin	Input Voltage	D	D = Ultra Wide Range, 18V-75V
Ra	Output Current	004A2	004A2 = 004.2 Amps Maximum Output Current
-	Output Voltage	S8R0	S8R0 = Special 8.0V nominal
	Pin Length		Omit = Default Pin Length shown in Mechanical Outline Figures 6 = Pin Length: 3.68 mm ± 0.25mm , (0.145 in. ± 0.010 in.) 8 = Pin Length: 2.79 mm ± 0.25mm , (0.110 in. ± 0.010 in.)
s	Action following Protective Shutdown	4	Omit = Latching Mode 4 = Auto-restart following shutdown (Overcurrent/Overvoltage)
ptions	On/Off Logic		Omit = Positive Logic 1 = Negative Logic
0	Customer Specific	XY	XY = Customer Specific Modified Code, Omit for Standard Code
	Mechanical Features	SR	Omit = Standard open Frame Module SR = Surface mount connections & tape/reel package
	RoHS	Z	Omit = RoHS 5/6, Lead Based Solder Used Z = RoHS 6/6 Compliant, Lead free

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